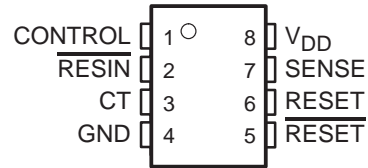


# TLC7701, TLC7725, TLC7703, TLC7733, TLC7705 MICROPOWER SUPPLY VOLTAGE SUPERVISORS

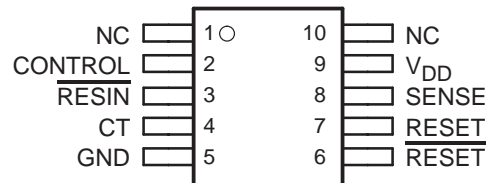
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- Power-On Reset Generator
- Automatic Reset Generation After Voltage Drop
- Precision Voltage Sensor
- Temperature-Compensated Voltage Reference
- Programmable Delay Time by External Capacitor
- Supply Voltage Range . . . 2 V to 6 V
- Defined  $\overline{\text{RESET}}$  Output from  $V_{DD} \geq 1 \text{ V}$
- Power-Down Control Support for Static RAM With Battery Backup
- Maximum Supply Current of 16  $\mu\text{A}$
- Power Saving Totem-Pole Outputs
- Temperature Range . . . Up to  $-55^\circ\text{C}$  to  $125^\circ\text{C}$

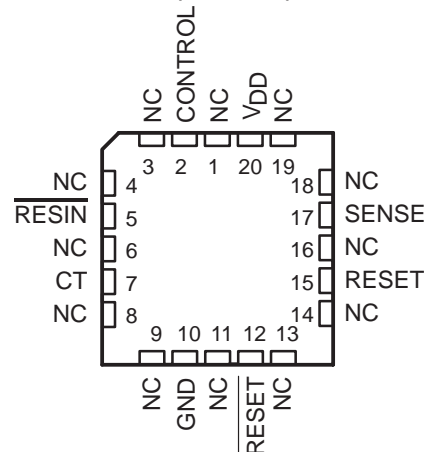
D, JG, P OR PW PACKAGE  
(TOP VIEW)



U PACKAGE  
(TOP VIEW)



FK PACKAGE  
(TOP VIEW)



## description

The TLC77xx family of micropower supply voltage supervisors provide reset control, primarily in microcomputer and microprocessor systems.

During power-on,  $\overline{\text{RESET}}$  is asserted when  $V_{DD}$  reaches 1 V. After minimum  $V_{DD}$  ( $\geq 2 \text{ V}$ ) is established, the circuit monitors SENSE voltage and keeps the reset outputs active as long as SENSE voltage ( $V_{I(\text{SENSE})}$ ) remains below the threshold voltage. An internal timer delays return of the output to the inactive state to ensure proper system reset. The delay time,  $t_d$ , is determined by an external capacitor:

$$t_d = 2.1 \times 10^4 \times C_T$$

Where

$C_T$  is in farads

$t_d$  is in seconds

Except for the TLC7701, which can be customized with two external resistors, each supervisor has a fixed SENSE threshold voltage set by an internal voltage divider. When SENSE voltage drops below the threshold voltage, the outputs become active and stay in that state until SENSE voltage returns above threshold voltage and the delay time,  $t_d$ , has expired.



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# TLC7701, TLC7725, TLC7703, TLC7733, TLC7705 MICROPOWER SUPPLY VOLTAGE SUPERVISORS

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## description (continued)

In addition to the power-on-reset and undervoltage-supervisor function, the TLC77xx adds power-down control support for static RAM. When CONTROL is tied to GND, RESET will act as active high. The voltage monitor contains additional logic intended for control of static memories with battery backup during power failure. By driving the chip select ( $\overline{CS}$ ) of the memory circuit with the RESET output of the TLC77xx and with the CONTROL driven by the memory bank select signal ( $\overline{CSH1}$ ) of the microprocessor (see Figure 10), the memory circuit is automatically disabled during a power loss. (In this application the TLC77xx power has to be supplied by the battery.)

The TLC77xxI is characterized for operation over a temperature range of  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ ; the TLC77xxQ is characterized for operation over a temperature range of  $-40^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ ; and the TLC77xxM is characterized for operation over the full Military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ .

### AVAILABLE OPTIONS

T <sub>A</sub>	THRESHOLD VOLTAGE (V)	PACKAGED DEVICES					
		SMALL OUTLINE (D) <sup>†</sup>	CHIP CARRIER (FK)	CERAMIC DIP (JG)	CERAMIC DUAL FLATPACK (U)	PLASTIC DIP (P)	THIN SHRINK SMALL OUTLINE (PW) <sup>‡</sup>
$-40^{\circ}\text{C}$ to $85^{\circ}\text{C}$	1.1	TLC7701ID	—	—	—	TLC7701IP	TLC7701IPWR
	2.25	TLC7725ID	—	—	—	TLC7725IP	TLC7725IPWR
	2.63	TLC7703ID	—	—	—	TLC7703IP	TLC7703IPWR
	2.93	TLC7733ID	—	—	—	TLC7733IP	TLC7733IPWR
	4.55	TLC7705ID	—	—	—	TLC7705IP	TLC7705IPWR
$-40^{\circ}\text{C}$ to $125^{\circ}\text{C}$	1.1	TLC7701QD	—	—	—	TLC7701QP	TLC7701QPWR
	2.25	TLC7725QD	—	—	—	TLC7725QP	TLC7725QPWR
	2.63	TLC7703QD	—	—	—	TLC7703QP	TLC7703QPWR
	2.93	TLC7733QD	—	—	—	TLC7733QP	TLC7733QPWR
	4.55	TLC7705QD	—	—	—	TLC7705QP	TLC7705QPWR
$-55^{\circ}\text{C}$ to $125^{\circ}\text{C}$	2.93	—	TLC7733MFK	TLC7733MJG	—	—	—
	4.55	—	TLC7705MFK	TLC7705MJG	TLC7705MU	—	—

<sup>†</sup> The D package is available taped and reeled. Add the suffix R to the device type when ordering (e.g., TLC7705QDR).

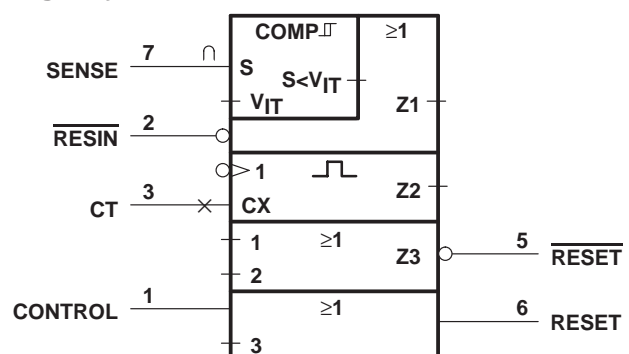
<sup>‡</sup> The PW package is only available left-end taped and reeled (indicated by the R suffix on the device type; e.g., TLC7705QPWR).

### FUNCTION TABLE

CONTROL	$\overline{RESIN}$	$V_I(\text{SENSE}) > V_{IT+}$	RESET	$\overline{RESET}$
L	L	False	H	L
L	L	True	H	L
L	H	False	H	L
L	H	True	L $\S$	H $\S$
H	L	False	H	L
H	L	True	H	L
H	H	False	H	L
H	H	True	H	H $\S$

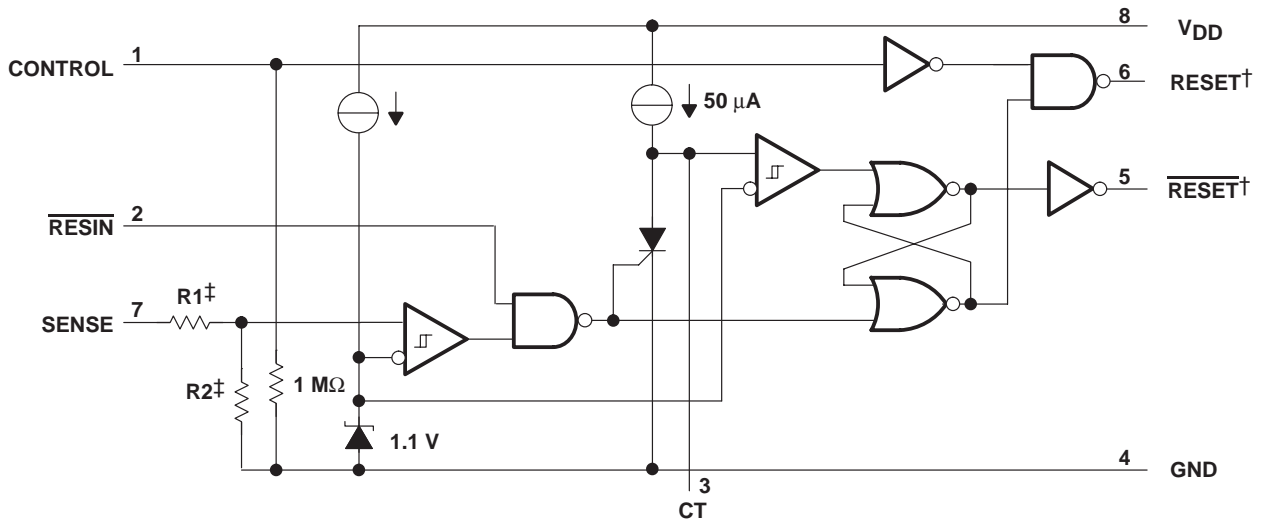
$\S$  RESET and  $\overline{RESET}$  states shown are valid for  $t > t_d$ .

### logic symbol<sup>¶</sup>



<sup>¶</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

functional block diagram

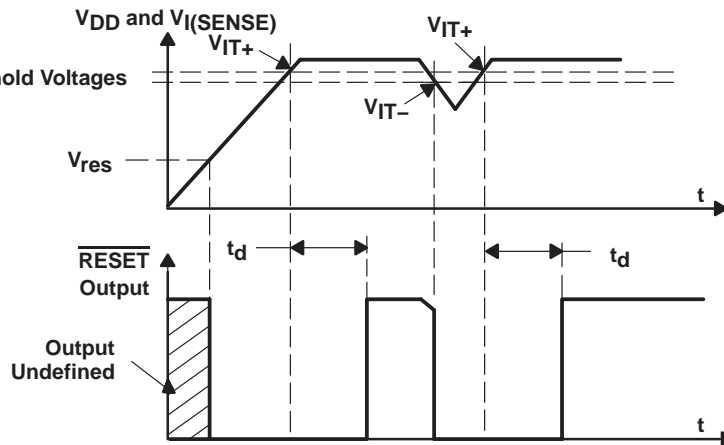


† Outputs are totem-pole configuration. External pullup or pulldown resistors are not required.

‡ Nominal values:

	R1 (Typ)	R2 (Typ)
TLC7701	0	$\infty$
TLC7725	600 k $\Omega$	600 k $\Omega$
TLC7703	698 k $\Omega$	502 k $\Omega$
TLC7733	750 k $\Omega$	450 k $\Omega$
TLC7705	910 k $\Omega$	290 k $\Omega$

timing diagram





# TLC7701, TLC7725, TLC7703, TLC7733, TLC7705 MICROPOWER SUPPLY VOLTAGE SUPERVISORS

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electrical characteristics over recommended operating conditions (see Note 2) (unless otherwise noted)

PARAMETER		TEST CONDITIONS	TLC77xx			UNIT	
			MIN	TYP†	MAX		
V <sub>OH</sub>	High-level output voltage	I <sub>OH</sub> = -20 μA	V <sub>DD</sub> = 2 V	1.8		V	
			V <sub>DD</sub> = 2.7 V	2.5			
			V <sub>DD</sub> = 4.5 V	4.3			
		I <sub>OH</sub> = -2 mA	V <sub>DD</sub> = 4.5 V	3.7			
V <sub>OL</sub>	Low-level output voltage	I <sub>OL</sub> = 20 μA	V <sub>DD</sub> = 2 V	0.2		V	
			V <sub>DD</sub> = 2.7 V	0.2			
			V <sub>DD</sub> = 4.5 V	0.2			
		I <sub>OL</sub> = 2 mA	V <sub>DD</sub> = 4.5 V	0.5			
V <sub>IT-</sub>	Negative-going input threshold voltage, SENSE (see Note 3)	TLC7701	V <sub>DD</sub> = 2 V to 6 V	1.04	1.1	1.16	V
		TLC7725		2.18	2.25	2.32	
		TLC7703		2.56	2.63	2.70	
		TLC7733		2.86	2.93	3	
		TLC7705		4.47	4.55	4.63	
V <sub>hys</sub>	Hysteresis voltage, SENSE	TLC7701	V <sub>DD</sub> = 2 V to 6 V	30		mV	
		TLC7725	V <sub>DD</sub> = 2 V to 6 V	70		mV	
		TLC7703,					
		TLC7733,					
		TLC7705					
V <sub>res</sub>	Power-up reset voltage‡	I <sub>OL</sub> = 20 μA			1	V	
I <sub>I</sub>	Input current	RESIN	V <sub>I</sub> = 0 V to V <sub>DD</sub>			2	μA
		CONTROL	V <sub>I</sub> = V <sub>DD</sub>	7		15	
		SENSE	V <sub>I</sub> = 5 V	5		10	
		SENSE, TLC7701 only	V <sub>I</sub> = 5 V			2	
I <sub>DD</sub>	Supply current	RESIN = V <sub>DD</sub> , SENSE = V <sub>DD</sub> ≥ V <sub>ITmax</sub> + 0.2 V CONTROL = 0 V, Outputs open		9		16	μA
I <sub>DD(d)</sub>	Supply current during t <sub>d</sub>	V <sub>DD</sub> = 5 V, V <sub>CT</sub> = 0, RESIN = V <sub>DD</sub> , SENSE = V <sub>DD</sub> , CONTROL = 0 V, Outputs open		120		150	μA
C <sub>I</sub>	Input capacitance, SENSE	V <sub>I</sub> = 0 V to V <sub>DD</sub>		50			pF

† Typical values apply at T<sub>A</sub> = 25°C.

‡ The lowest supply voltage at which RESET becomes active. The symbol V<sub>RES</sub> is not currently listed within EIA or JEDEC standards for semiconductor symbology. Rise time of V<sub>DD</sub> ≥ 15 μs/V.

NOTES: 2. All characteristics are measured with C<sub>T</sub> = 0.1 μF.

3. To ensure best stability of the threshold voltage, a bypass capacitor (ceramic, 0.1 μF) should be connected near the supply terminals.

# TLC7701, TLC7725, TLC7703, TLC7733, TLC7705 MICROPOWER SUPPLY VOLTAGE SUPERVISORS

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electrical characteristics over recommended operating conditions (see Note 2) (unless otherwise noted)

PARAMETER		TEST CONDITIONS		TLC77xxM			UNIT	
				MIN	TYP†	MAX		
V <sub>OH</sub>	High-level output voltage	I <sub>OH</sub> = -20 μA	V <sub>DD</sub> = 2 V,	T <sub>A</sub> = 25°C	1.8		V	
				T <sub>A</sub> = -55°C to 125°C	1.7			
			V <sub>DD</sub> = 2.7 V	T <sub>A</sub> = 25°C	2.5			
				T <sub>A</sub> = -55°C to 125°C	2.3			
			V <sub>DD</sub> = 4.5 V	T <sub>A</sub> = 25°C	4.3			
				T <sub>A</sub> = -55°C to 125°C	4.2			
I <sub>OH</sub> = -2 mA	V <sub>DD</sub> = 4.5 V	T <sub>A</sub> = 25°C	3.7					
		T <sub>A</sub> = -55°C to 125°C	3.6					
V <sub>OL</sub>	Low-level output voltage	I <sub>OL</sub> = 20 μA	V <sub>DD</sub> = 2 V	T <sub>A</sub> = 25°C	0.2		V	
				T <sub>A</sub> = -55°C to 125°C	0.2			
			V <sub>DD</sub> = 2.7 V	T <sub>A</sub> = 25°C	0.2			
				T <sub>A</sub> = -55°C to 125°C	0.2			
			V <sub>DD</sub> = 4.5 V	T <sub>A</sub> = 25°C	0.2			
				T <sub>A</sub> = -55°C to 125°C	0.2			
			I <sub>OL</sub> = 2 mA	V <sub>DD</sub> = 4.5 V	T <sub>A</sub> = 25°C	0.5		
					T <sub>A</sub> = -55°C to 125°C	0.5		
V <sub>IT-</sub>	Negative-going input threshold voltage, SENSE (see Note 3)	TLC7733	V <sub>DD</sub> = 2 V to 6 V	2.86	2.93	3.1	V	
		TLC7705		4.3	4.5	4.8		
V <sub>hys</sub>	Hysteresis voltage, SENSE	V <sub>DD</sub> = 2 V to 6 V	V <sub>DD</sub> = 2 V to 6 V	70		mV		
V <sub>res</sub>	Power-up reset voltage‡	I <sub>OL</sub> = 20 μA		1		V		
I <sub>I</sub>	Input current	RESIN	V <sub>I</sub> = 0 V to V <sub>DD</sub>	2		μA		
		CONTROL	V <sub>I</sub> = V <sub>DD</sub>	7	15			
		SENSE	V <sub>I</sub> = 5 V	5	10			
		SENSE, TLC7701 only	V <sub>I</sub> = 5 V	2				
I <sub>DD</sub>	Supply current	RESIN = V <sub>DD</sub> , SENSE = V <sub>DD</sub> ≥ V <sub>ITmax</sub> + 0.2 V CONTROL = 0 V, Outputs open		9	16	μA		
I <sub>DD(d)</sub>	Supply current during t <sub>d</sub>	TLC7733	V <sub>CT</sub> = 0, RESIN = V <sub>DD</sub> , CONTROL = 0 V,	V <sub>DD</sub> = 3.3 V	250		μA	
		TLC7705	SENSE = V <sub>DD</sub> , Outputs open	V <sub>DD</sub> = 5 V	120	150		
C <sub>I</sub>	Input capacitance, SENSE	V <sub>I</sub> = 0 V to V <sub>DD</sub>		50		pF		

† Typical values apply at T<sub>A</sub> = 25°C.

‡ The lowest supply voltage at which RESET becomes active. The symbol V<sub>res</sub> is not currently listed within EIA or JEDEC standards for semiconductor symbology. Rise time of V<sub>DD</sub> ≥ 15 μs/V.

NOTES: 2. All characteristics are measured with C<sub>T</sub> = 0.1 μF.

3. To ensure best stability of the threshold voltage, a bypass capacitor (ceramic, 0.1 μF) should be placed near the supply terminals.

# TLC7701, TLC7725, TLC7703, TLC7733, TLC7705 MICROPOWER SUPPLY VOLTAGE SUPERVISORS

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switching characteristics at  $V_{DD} = 5\text{ V}$ ,  $R_L = 2\text{ k}\Omega$ ,  $C_L = 50\text{ pF}$ ,  $T_A = 25^\circ\text{C}$  (unless otherwise noted)

PARAMETER	MEASURED		TEST CONDITIONS	TLC77xx			UNIT
	FROM (INPUT)	TO (OUTPUT)		MIN	TYP	MAX	
$t_d$ Delay time	$V_{I(\text{SENSE})} \geq V_{IT+}$	RESET and RESET	$\overline{\text{RESIN}} = 0.7 \times V_{DD}$ , CONTROL = $0.2 \times V_{DD}$ , $C_T = 100\text{ nF}$ , $T_A = \text{Full range}$ , See timing diagram	1.1	2.1	4.2	ms
$t_{PLH}$ Propagation delay time, low-to-high-level output	SENSE	$\overline{\text{RESET}}$	$V_{IH} = V_{IT+max} + 0.2\text{ V}$ , $V_{IL} = V_{IT\_min} - 0.2\text{ V}$ , $\overline{\text{RESIN}} = 0.7 \times V_{DD}$ , CONTROL = $0.2 \times V_{DD}$ , $C_T = NCT^\dagger$			20	$\mu\text{s}$
$t_{PHL}$ Propagation delay time, high-to-low-level output		$\overline{\text{RESET}}$				5	
$t_{PLH}$ Propagation delay time, low-to-high-level output		RESET				5	
$t_{PHL}$ Propagation delay time, high-to-low-level output		RESET				20	
$t_{PLH}$ Propagation delay time, low-to-high-level output	$\overline{\text{RESIN}}$	$\overline{\text{RESET}}$	$V_{IH} = 0.7 \times V_{DD}$ , $V_{IL} = 0.2 \times V_{DD}$ , SENSE = $V_{IT+max} + 0.2\text{ V}$ , CONTROL = $0.2 \times V_{DD}$ , $C_T = NCT^\dagger$			20	$\mu\text{s}$
$t_{PHL}$ Propagation delay time, high-to-low-level output		$\overline{\text{RESET}}$				40	ns
$t_{PLH}$ Propagation delay time, low-to-high-level output		RESET				45	
$t_{PHL}$ Propagation delay time, high-to-low-level output		RESET				20	$\mu\text{s}$
$t_{PLH}$ Propagation delay time, low-to-high-level output	CONTROL	RESET	$V_{IH} = 0.7 \times V_{DD}$ , $V_{IL} = 0.2 \times V_{DD}$ , SENSE = $V_{IT+max} + 0.2\text{ V}$ , $\overline{\text{RESIN}} = 0.7 \times V_{DD}$ , $C_T = NCT^\dagger$			38	ns
$t_{PHL}$ Propagation delay time, high-to-low-level output							38
Low-level minimum pulse duration to switch RESET and RESET	SENSE		$V_{IH} = V_{IT+max} + 0.2\text{ V}$ , $V_{IL} = V_{IT\_min} - 0.2\text{ V}$ , $V_{IL} = 0.2 \times V_{DD}$ , $V_{IH} = 0.7 \times V_{DD}$	3			$\mu\text{s}$
	$\overline{\text{RESIN}}$			1			
$t_r$ Rise time		RESET and RESET	10% to 90%		8		ns/V
$t_f$ Fall time		RESET and RESET	90% to 10%		4		

$^\dagger$  NC = No capacitor, and includes up to 100-pF probe and jig capacitance.

# TLC7701, TLC7725, TLC7703, TLC7733, TLC7705 MICROPOWER SUPPLY VOLTAGE SUPERVISORS

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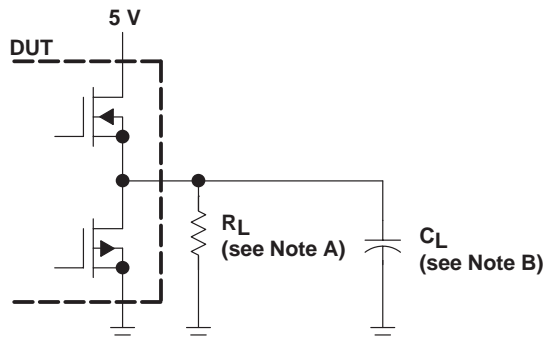
switching characteristics at  $V_{DD} = 5\text{ V}$ ,  $R_L = 2\text{ k}\Omega$ ,  $C_L = 50\text{ pF}$

PARAMETER	MEASURED		TEST CONDITIONS	$T_A$	TLC77xxM			UNIT
	FROM (INPUT)	TO (OUTPUT)			MIN	TYP	MAX	
$t_d$ Delay time	$V_I(\text{SENSE}) \geq V_{IT+}$	RESET and RESET	RESIN = 2.7 V, CONTROL = 0.4 V, $C_T = 100\text{ nF}$ , See timing diagram	Full range	1.1	2.1	4.2	ms
$t_{PLH}$ Propagation delay time, low-to-high-level output	SENSE	RESET	$V_{IH} = V_{IT+max} + 0.2\text{ V}$ , $V_{IL} = V_{IT-min} - 0.2\text{ V}$ , RESIN = 2.7 V, CONTROL = 0.4 V, $C_T = \text{NC}^\dagger$	25°C			20	$\mu\text{s}$
		Full range				24		
		RESET		25°C			5	$\mu\text{s}$
		Full range				7		
$t_{PHL}$ Propagation delay time, high-to-low-level output	SENSE	RESET	$V_{IH} = V_{IT+max} + 0.2\text{ V}$ , $V_{IL} = V_{IT-min} - 0.2\text{ V}$ , RESIN = 2.7 V, CONTROL = 0.4 V, $C_T = \text{NC}^\dagger$	25°C			5	$\mu\text{s}$
		Full range				7		
		RESET		25°C			20	$\mu\text{s}$
		Full range				24		
$t_{PLH}$ Propagation delay time, low-to-high-level output	RESIN	RESET	$V_{IH} = 2.7\text{ V}$ , $V_{IL} = 0.4\text{ V}$ , SENSE = $V_{IT+max} + 0.2\text{ V}$ , CONTROL = 0.4 V, $C_T = \text{NC}^\dagger$	25°C			20	$\mu\text{s}$
		Full range				24		
		RESET		25°C			45	ns
		Full range				65		
$t_{PHL}$ Propagation delay time, high-to-low-level output	RESIN	RESET	$V_{IH} = 2.7\text{ V}$ , $V_{IL} = 0.4\text{ V}$ , SENSE = $V_{IT+max} + 0.2\text{ V}$ , CONTROL = 0.4 V, $C_T = \text{NC}^\dagger$	25°C			40	ns
		Full range				60		
		RESET		25°C			20	$\mu\text{s}$
		Full range				24		
$t_{PLH}$ Propagation delay time, low-to-high-level output	CONTROL	RESET	$V_{IH} = 2.7\text{ V}$ , $V_{IL} = 0.4\text{ V}$ , SENSE = $V_{IT+max} + 0.2\text{ V}$ , RESIN = 2.7 V, $C_T = \text{NC}^\dagger$	25°C			38	ns
Full range						58		
$t_{PHL}$ Propagation delay time, high-to-low-level output				25°C			38	ns
Full range						58		
Low-level minimum pulse duration	SENSE		$V_{IH} = V_{IT+max} + 0.2\text{ V}$ , $V_{IL} = V_{IT-min} - 0.2\text{ V}$ , $V_{IL} = 0.4\text{ V}$ , $V_{IH} = 2.7\text{ V}$	Full range	3			$\mu\text{s}$
	RESIN				1			
$t_r$ Rise time		RESET and RESET	10% to 90%	Full range	8			ns/V
$t_f$ Fall time			90% to 10%		4			

$^\dagger$  NC = No capacitor, and includes up to 100-pF probe and jig capacitance.



PARAMETER MEASUREMENT INFORMATION



NOTES: A. For switching characteristics,  $R_L = 2\text{ k}\Omega$ .  
B.  $C_L = 50\text{ pF}$  includes jig and probe capacitance.

Figure 1. RESET AND  $\overline{\text{RESET}}$  Output Configurations

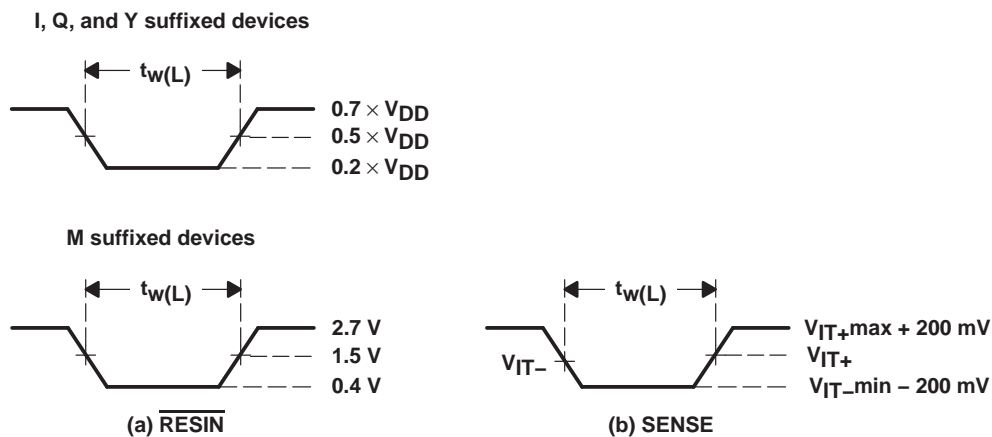


Figure 2. Input Pulse Definition Waveforms

# TLC7701, TLC7725, TLC7703, TLC7733, TLC7705 MICROPOWER SUPPLY VOLTAGE SUPERVISORS

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## TYPICAL CHARACTERISTICS

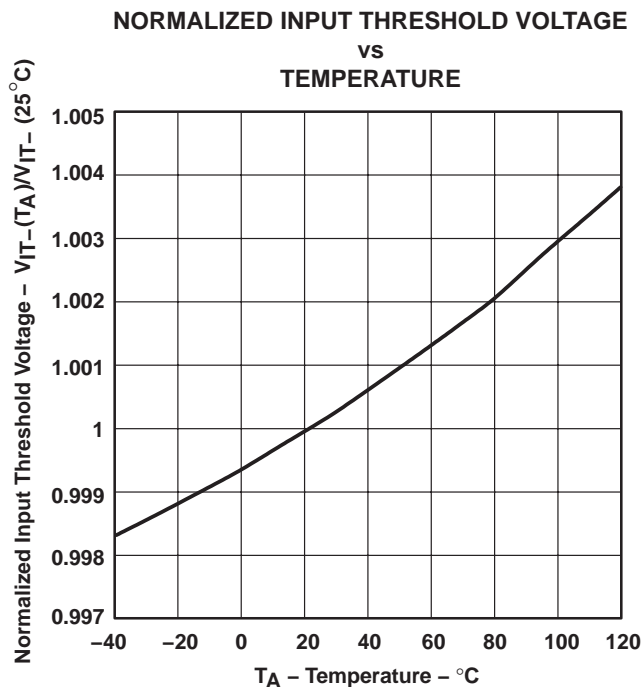


Figure 3

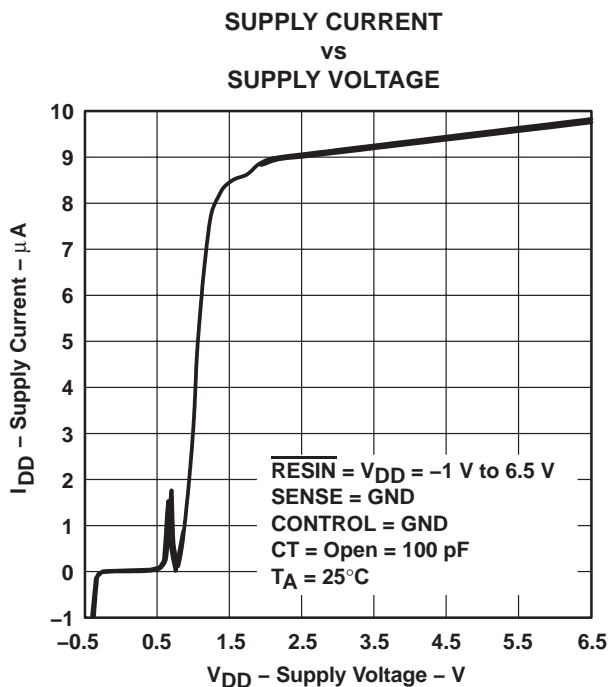


Figure 4

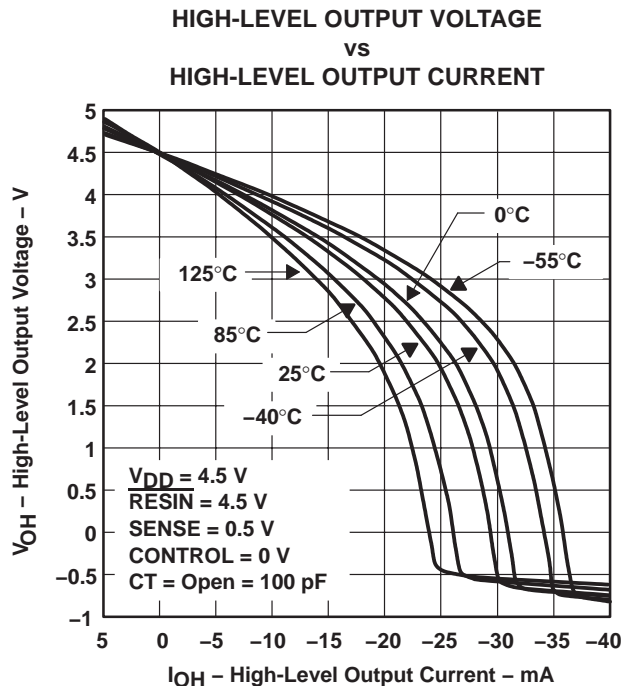


Figure 5

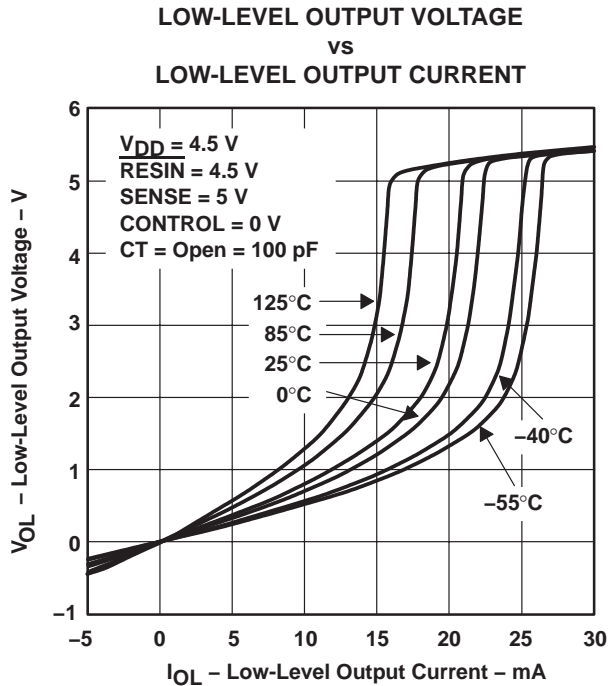
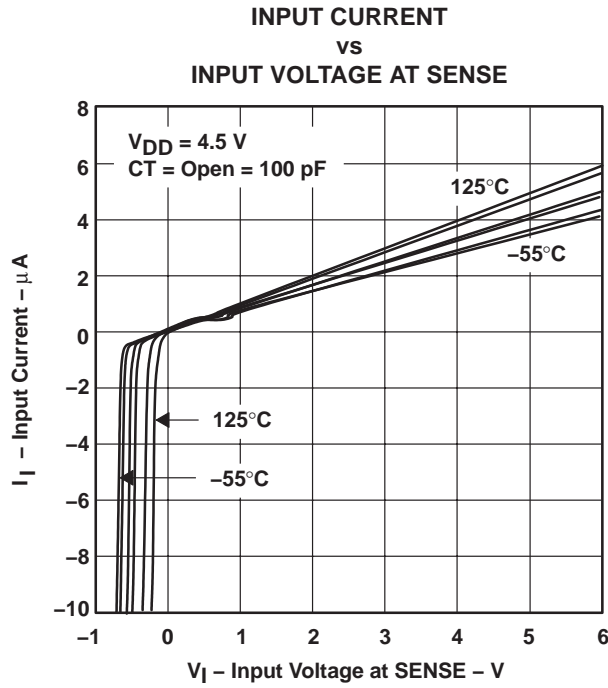
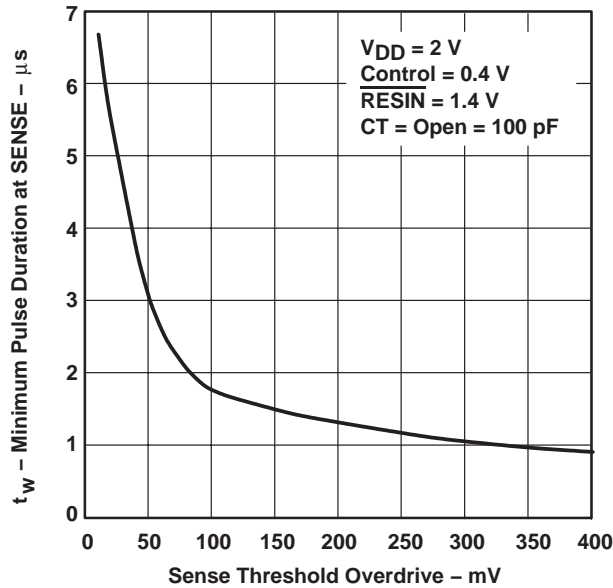


Figure 6

TYPICAL CHARACTERISTICS



**MINIMUM PULSE DURATION AT SENSE  
vs  
SENSE THRESHOLD OVERDRIVE**



# TLC7701, TLC7725, TLC7703, TLC7733, TLC7705 MICROPOWER SUPPLY VOLTAGE SUPERVISORS

SLVS087L – DECEMBER 1994 – REVISED FEBRUARY 2003

## APPLICATION INFORMATION

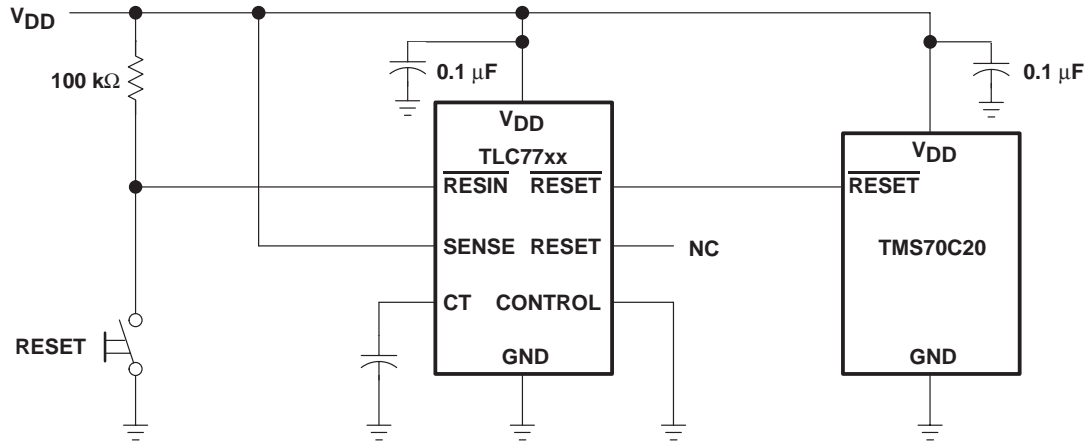


Figure 9. Reset Controller in a Microcomputer System

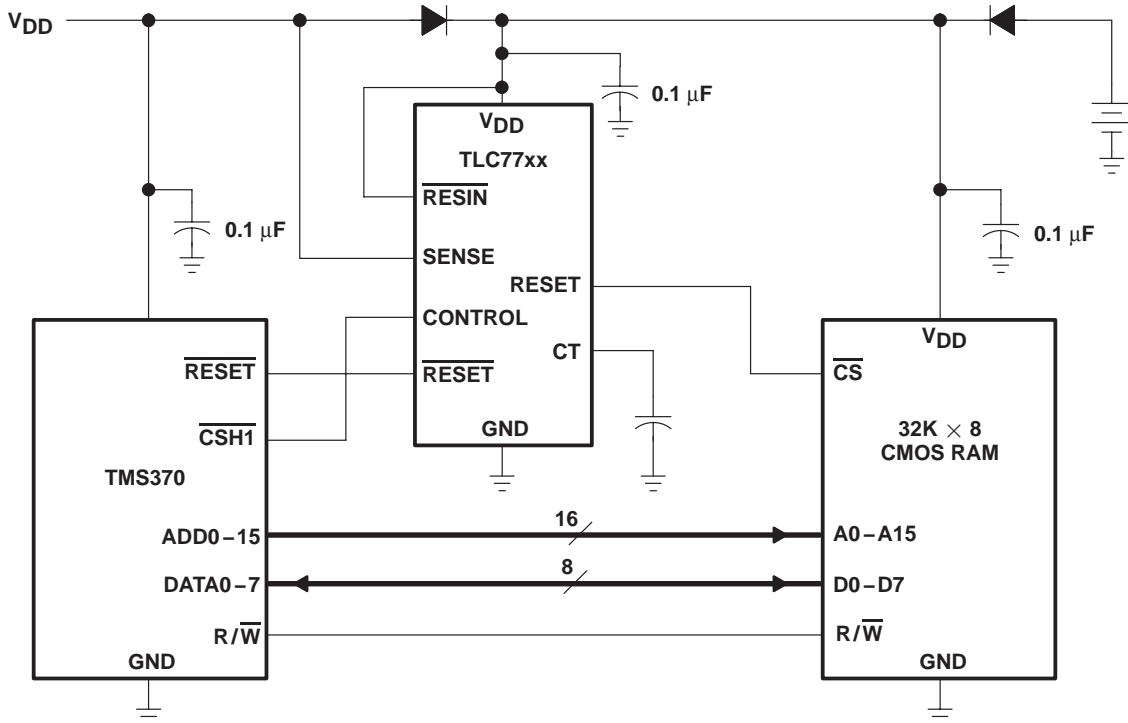


Figure 10. Data Retention During Power Down Using Static CMOS RAMs



**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-9750901Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9750901QPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type
5962-9751301Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9751301QHA	ACTIVE	CFP	U	10	1	TBD	A42	N / A for Pkg Type
5962-9751301QPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type
TLC7701ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7701IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7701IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7701IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7701IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7701IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7701IPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7701IPWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7701IPWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI
TLC7701IPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7701IPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7701IQD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7701IQDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7701IQDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7701IQDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7701IQP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7701IQPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7701IQPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7701IQPWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7701IQPWLE	PREVIEW	TSSOP	PW	8		TBD	Call TI	Call TI
TLC7701IQPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7701IQPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7703ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
						no Sb/Br)		
TLC7703IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7703IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7703IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7703IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7703IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7703IPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7703IPWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7703IPWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI
TLC7703IPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7703IPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7703QD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7703QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7703QP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7703QPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7703QPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7703QPWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7705ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7705IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7705IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7705IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7705IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7705IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7705IPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7705IPWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7705IPWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI
TLC7705IPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TLC7705IPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7705MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
TLC7705MJG	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type
TLC7705MJGB	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type
TLC7705MUB	ACTIVE	CFP	U	10	1	TBD	A42	N / A for Pkg Type
TLC7705QD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7705QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7705QDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7705QDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7705QP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7705QPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7705QPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7705QPWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7705QPWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI
TLC7705QPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7705QPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7725ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7725IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7725IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7725IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7725IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7725IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7725IPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7725IPWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7725IPWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI
TLC7725IPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7725IPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7725QD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TLC7725QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7725QDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7725QDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7725QP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7725QPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7725QPWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI
TLC7725QPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7725QPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7733ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7733IDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7733IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7733IDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7733IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7733IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7733IPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7733IPWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7733IPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7733IPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7733MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
TLC7733MJG	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type
TLC7733MJGB	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type
TLC7733QD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7733QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7733QDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7733QDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7733QP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7733QPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7733QPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM



Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
						no Sb/Br)		
TLC7733QPWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7733QPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7733QPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF TLC7701, TLC7705, TLC7705M, TLC7733, TLC7733M :**

- Automotive: [TLC7701-Q1](#), [TLC7705-Q1](#), [TLC7733-Q1](#)
- Enhanced Product: [TLC7701-EP](#), [TLC7705-EP](#), [TLC7733-EP](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

**TAPE AND REEL INFORMATION**



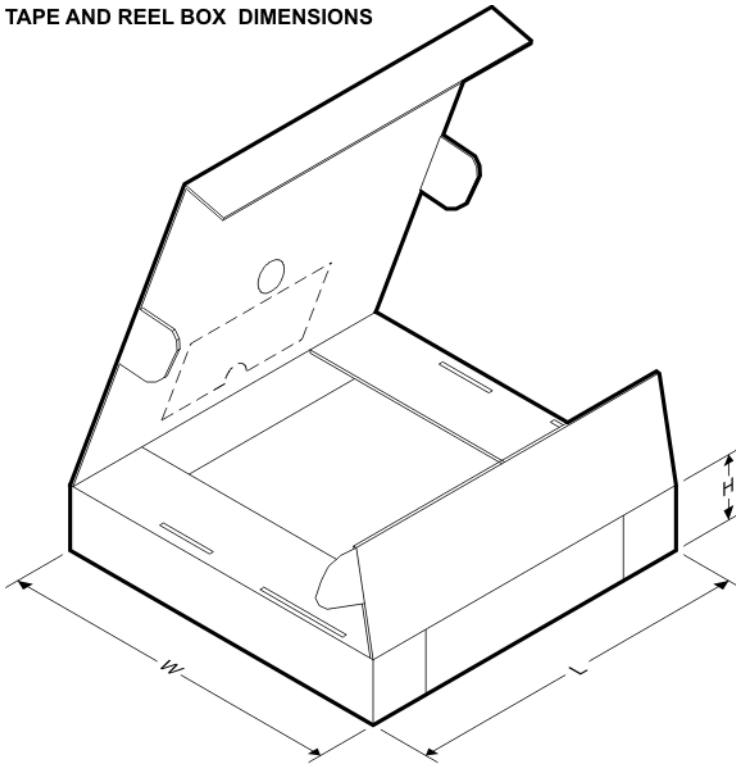
**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC7701IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC7701IPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TLC7701QDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC7701QPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TLC7703IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC7703IPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TLC7705IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC7705IPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TLC7705QDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC7705QPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TLC7725IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC7725IPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TLC7725QDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC7725QPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TLC7733IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC7733IPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TLC7733QDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TLC7733QPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**

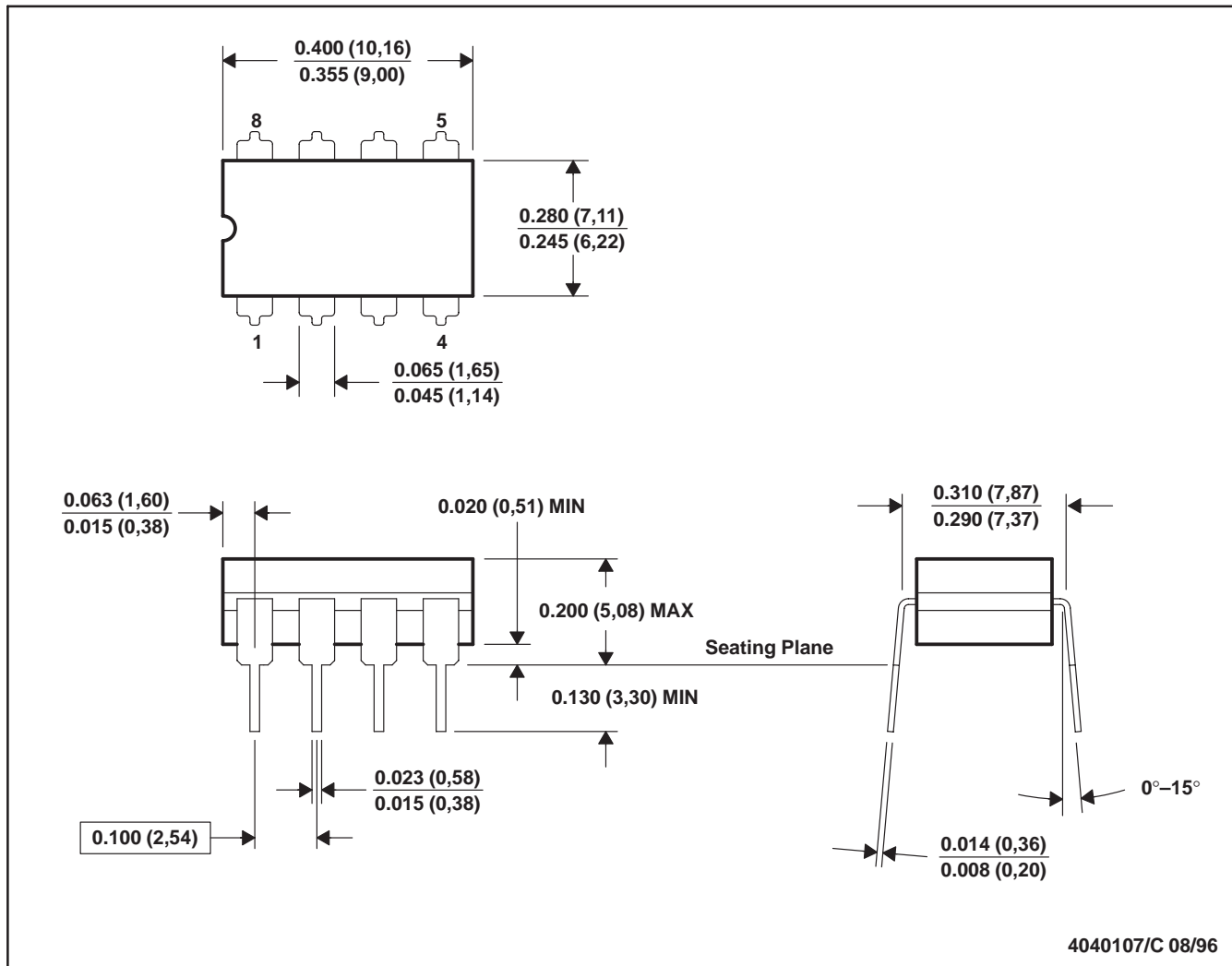


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC7701IDR	SOIC	D	8	2500	346.0	346.0	29.0
TLC7701IPWR	TSSOP	PW	8	2000	346.0	346.0	29.0
TLC7701QDR	SOIC	D	8	2500	346.0	346.0	29.0
TLC7701QPWR	TSSOP	PW	8	2000	346.0	346.0	29.0
TLC7703IDR	SOIC	D	8	2500	346.0	346.0	29.0
TLC7703IPWR	TSSOP	PW	8	2000	346.0	346.0	29.0
TLC7705IDR	SOIC	D	8	2500	346.0	346.0	29.0
TLC7705IPWR	TSSOP	PW	8	2000	346.0	346.0	29.0
TLC7705QDR	SOIC	D	8	2500	346.0	346.0	29.0
TLC7705QPWR	TSSOP	PW	8	2000	346.0	346.0	29.0
TLC7725IDR	SOIC	D	8	2500	346.0	346.0	29.0
TLC7725IPWR	TSSOP	PW	8	2000	346.0	346.0	29.0
TLC7725QDR	SOIC	D	8	2500	346.0	346.0	29.0
TLC7725QPWR	TSSOP	PW	8	2000	346.0	346.0	29.0
TLC7733IDR	SOIC	D	8	2500	346.0	346.0	29.0
TLC7733IPWR	TSSOP	PW	8	2000	346.0	346.0	29.0
TLC7733QDR	SOIC	D	8	2500	346.0	346.0	29.0
TLC7733QPWR	TSSOP	PW	8	2000	346.0	346.0	29.0

JG (R-GDIP-T8)

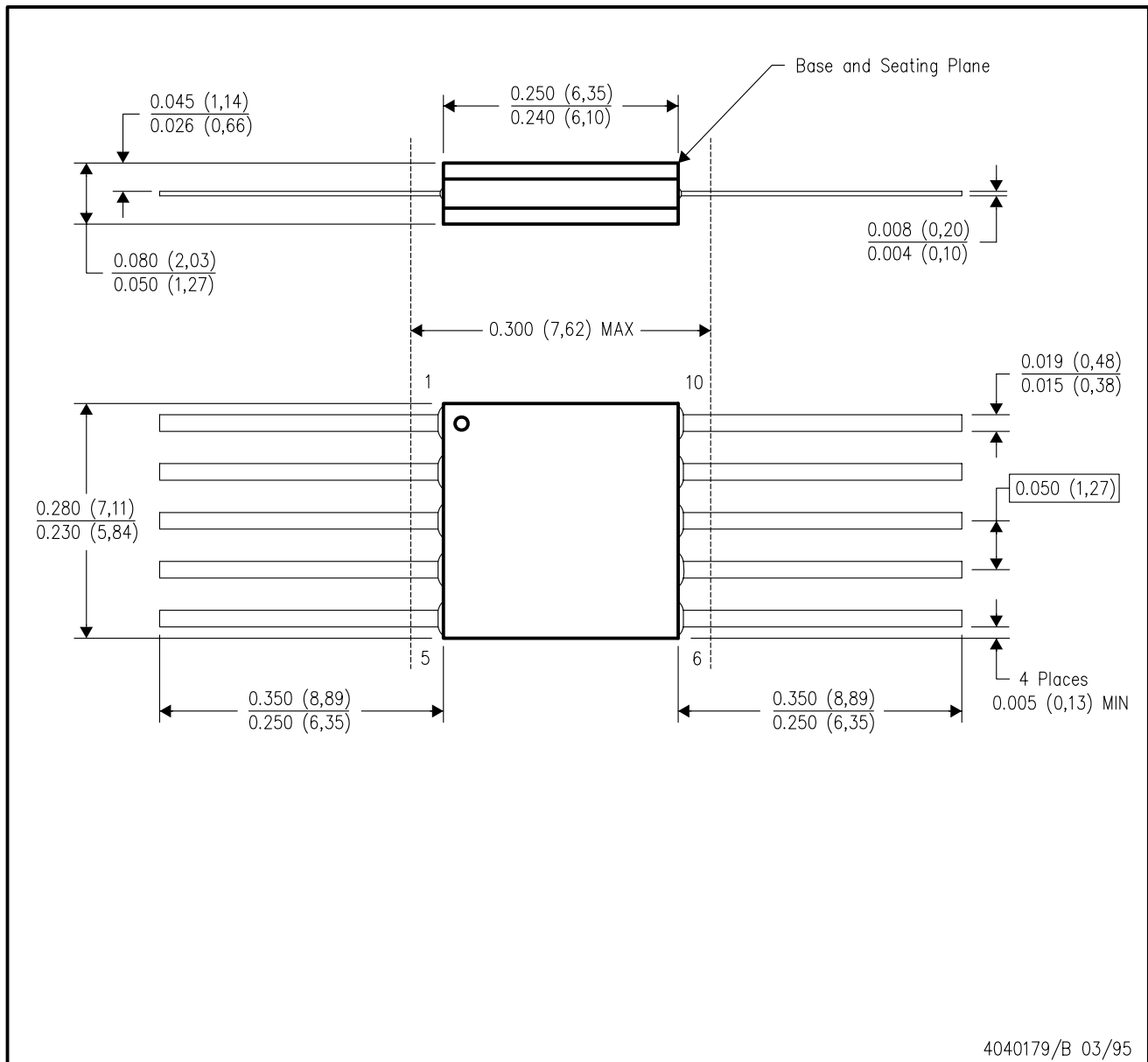
CERAMIC DUAL-IN-LINE



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for terminal identification.  
 E. Falls within MIL STD 1835 GDIP1-T8

U (S-GDFP-F10)

CERAMIC DUAL FLATPACK

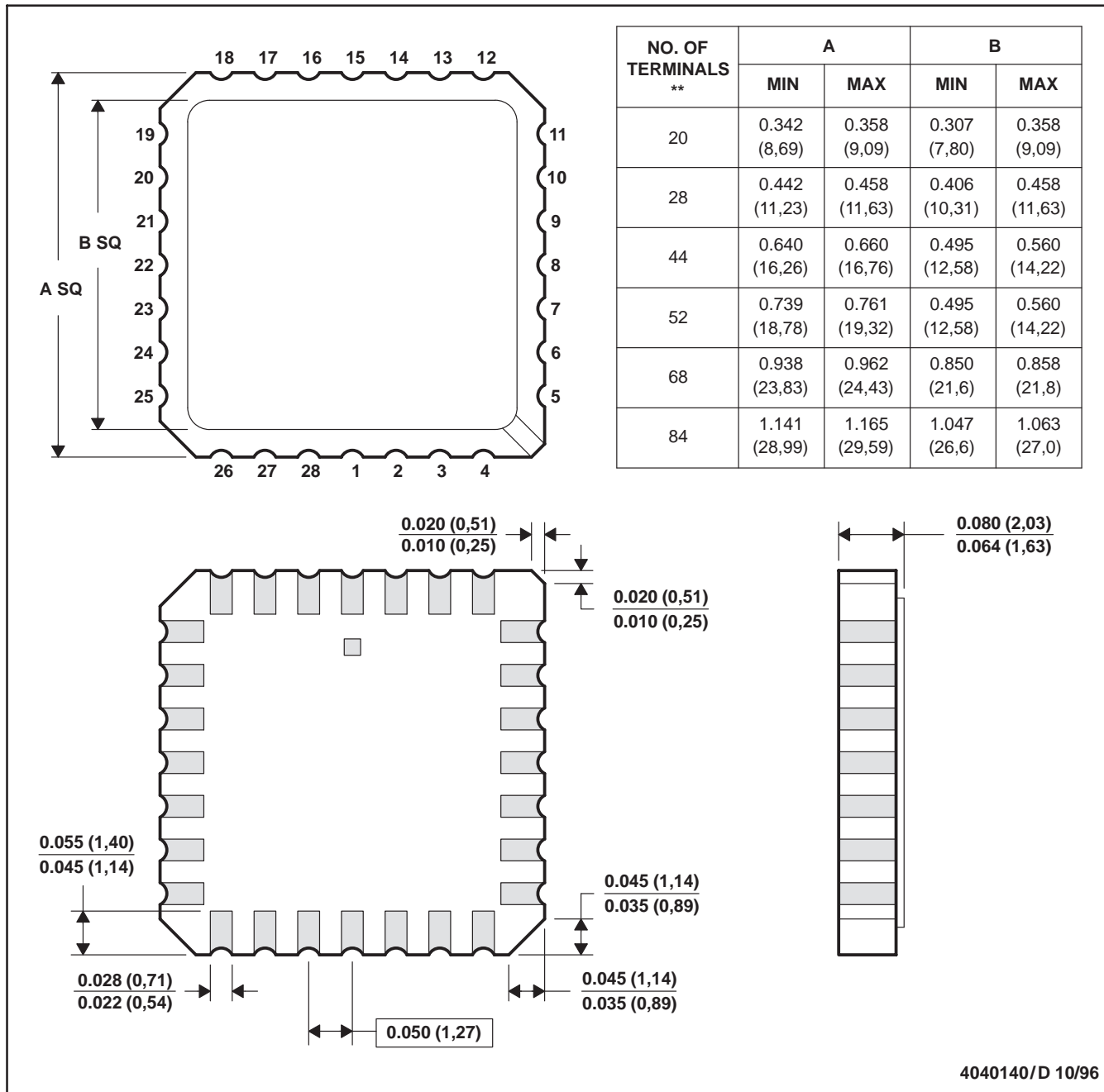


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F10 and JEDEC MO-092AA

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

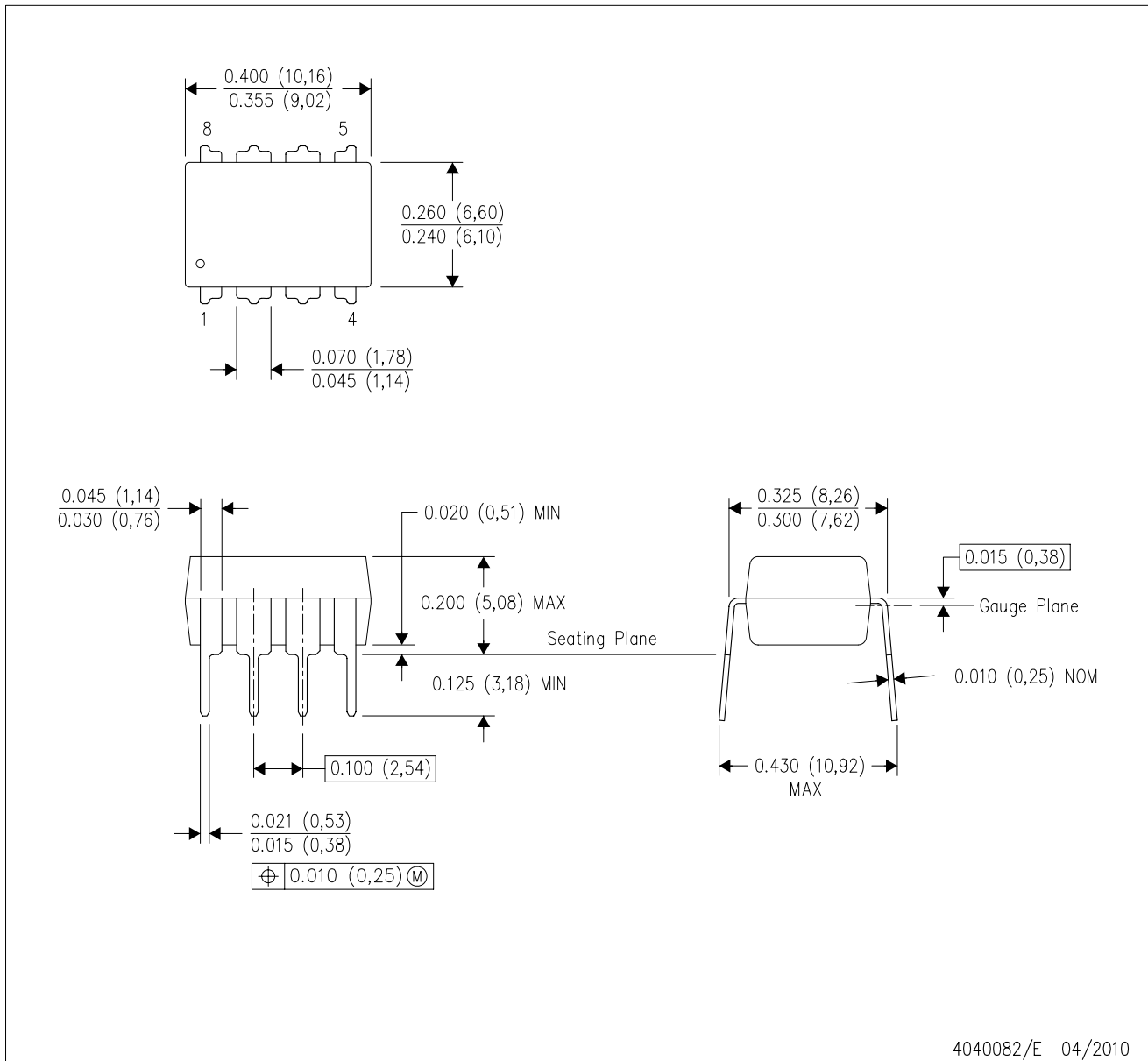
28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004

P (R-PDIP-T8)

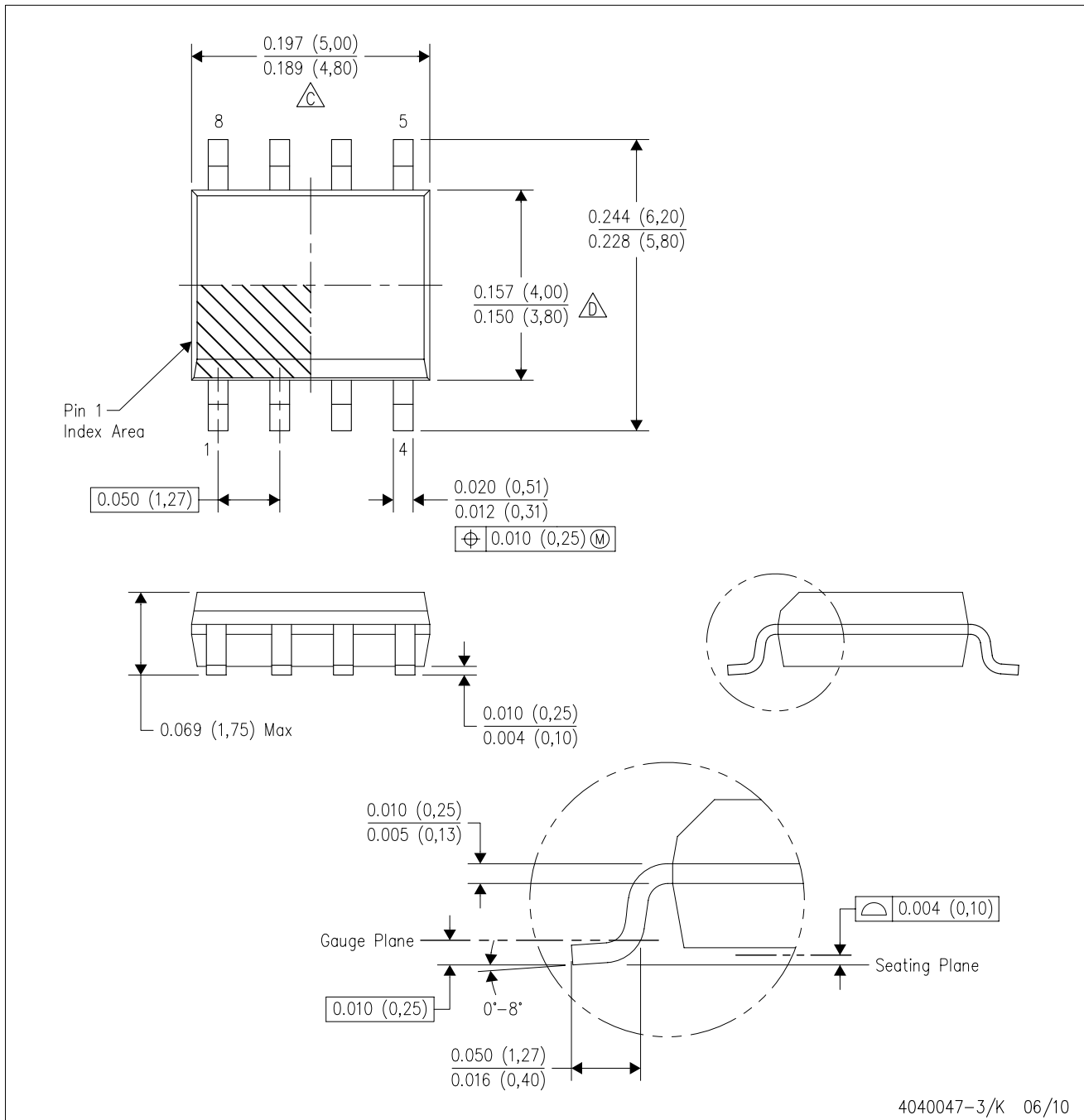
PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MS-001 variation BA.

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE

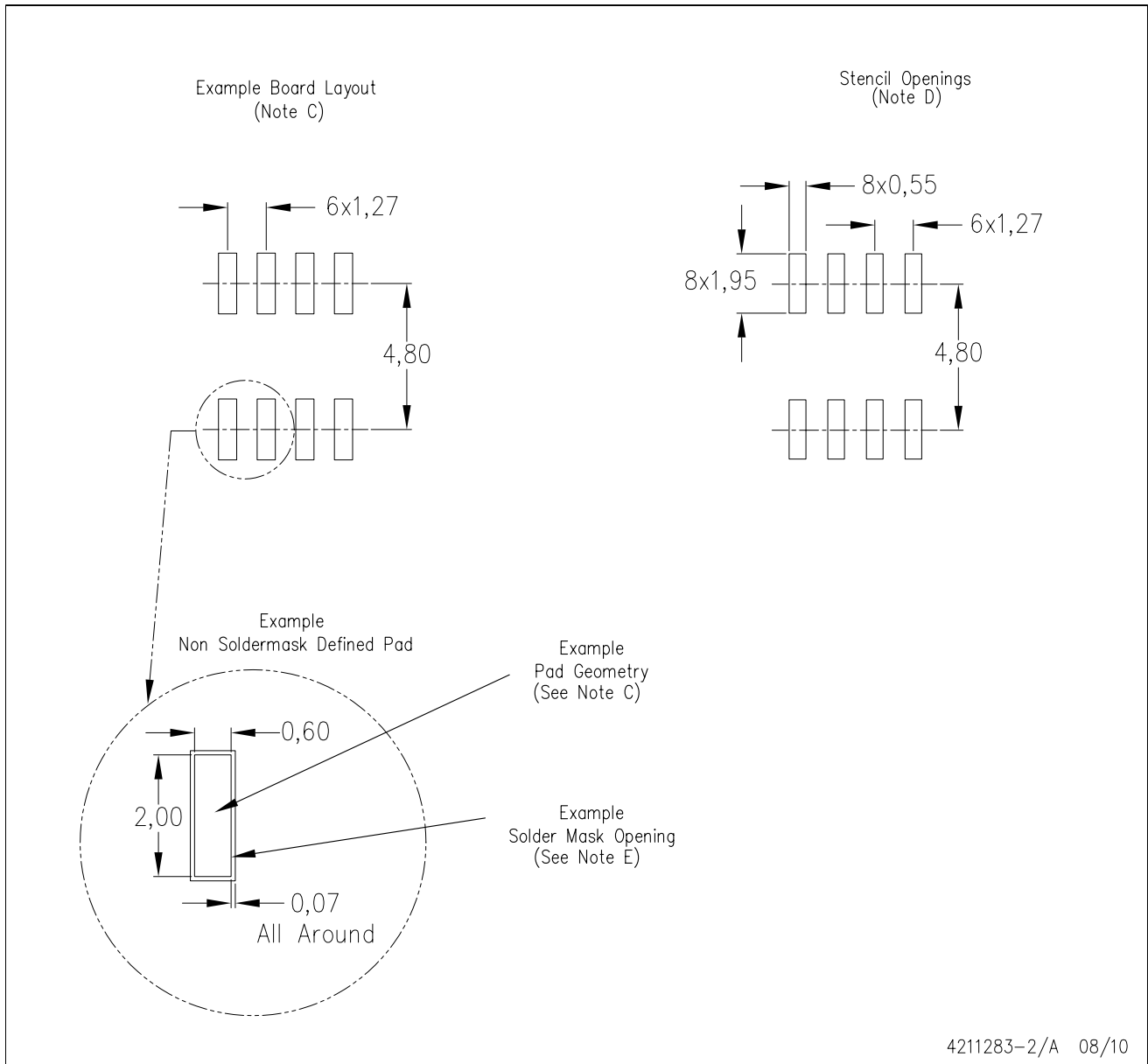


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
  - E. Reference JEDEC MS-012 variation AA.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE

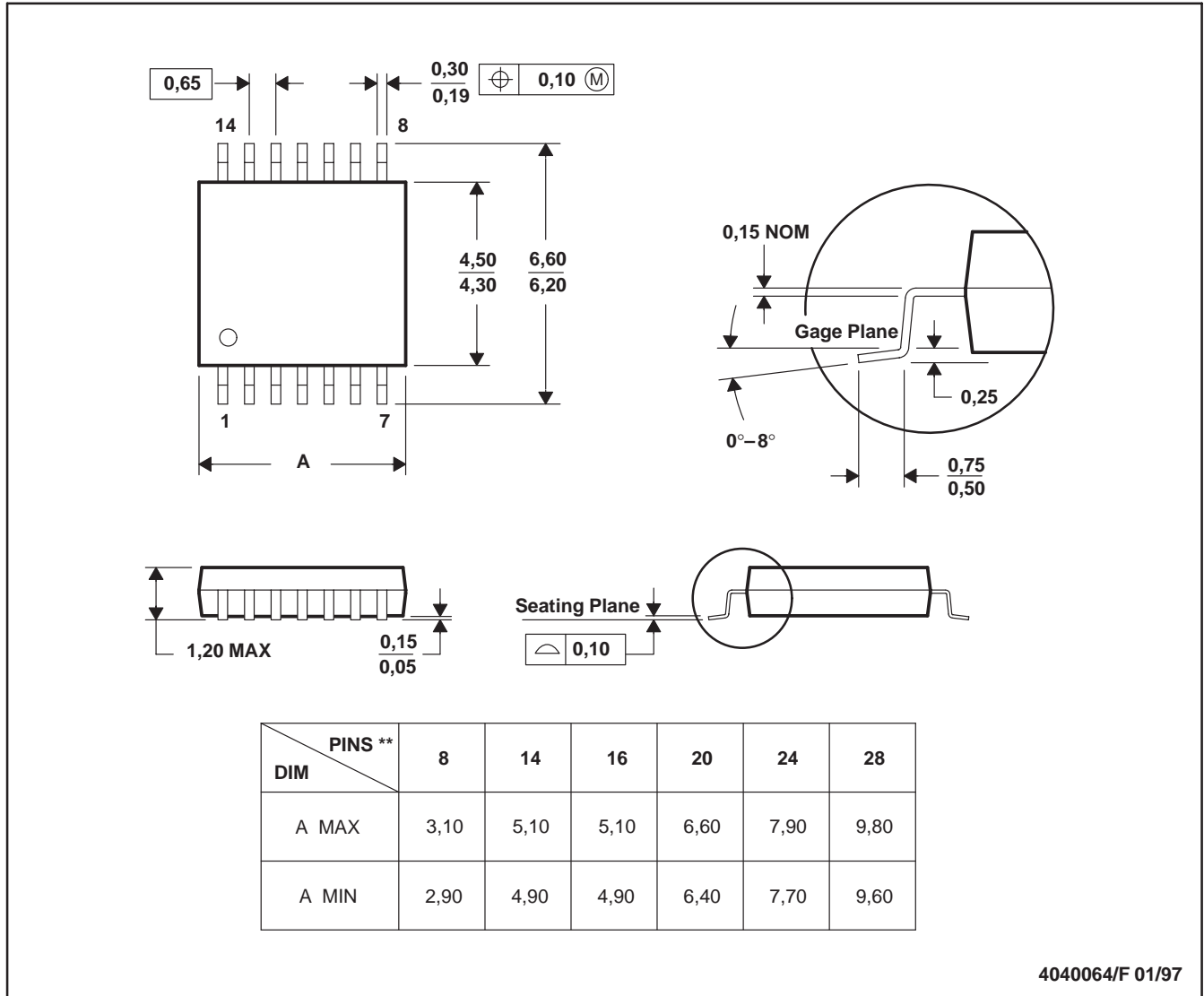


- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>	Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>	Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>	Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>	Energy	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>	Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>	Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>	Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>	Space, Avionics & Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
RF/IF and ZigBee® Solutions	<a href="http://www.ti.com/lprf">www.ti.com/lprf</a>	Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>
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